Low-profile and compact size of 3.7×3.7×0.35mm





■ Typical Specifications

Items	Specifications
Rating (max.)	50mA 12V DC
Rating (min.)	10 µA 1V DC
Initial contact resistance	100mΩ max.
Travel (mm)	0.15

Product Line

Product No.	Operating force	Operating direction	Operating life	Minimum order unit (pcs.)	
Product No.	Operating force	Operating direction	(5mA 5V DC)	Japan	Export
SKRWAEE030	1.57N	Top push	500,000 cycles	10.000	10.000
SKRWADE030	2.35N	τορ βάδιτ	50,000 cycles	10,000	10,000

Packing Specifications

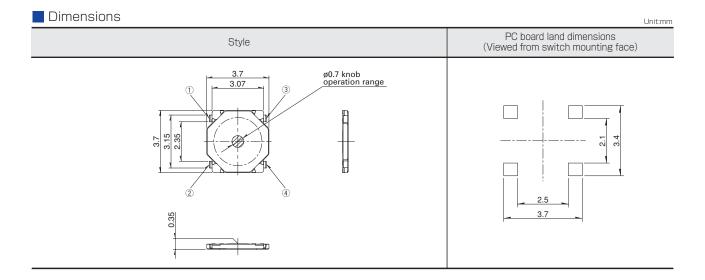
Taping

Number of packages (pcs.)			Tape width	Export package
1 reel	1 case / Japan	1 case / export packing	(mm)	measurements (mm)
10,000	100,000	100,000	12	401×401×214

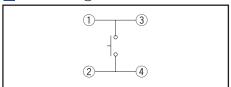
Unit:mm Reel size

Note

For reels of 330mm diameter, please inquire.



Circuit Diagram



	Type				Sharp Fee	eling Type				
	Турс	Surface Mount								
	Series	SKSH	SKRW	SKRM	SKRB	SKRR	SKQG	SKTC	SKSK	
	Photo						-		Q.	
	Features		Low-	profile		Low-profile and long life	Low-profile	Double	action	
	Water-proof	_	_	_	_	_	_	•	_	
	Dust-proof	_	_	_	_	_	_	•	_	
	IP standard	_	_	_	_	_	_	67 equivalency	_	
Operatir	Top push	•	•	•	•	•	•	•	•	
directio	Side push	_	_	_	_	_	_	_	_	
	W	3.3				7.5		3.4	3.5	
Dimensio (mm)	ons D	2.9	∃3.7	□4.5	□4.8	7	- □5.2	2.2	3.2	
	Н	0.	35	0.4	0.55	0.6	0.8/1.5	0.62	0.6	
Operation force coverage	2N to 3N	1		Į.		\$		See the releving respective description	e product	
	Travel (mm)	0.	15	0.15	/0.2	0.	25	See the relevant pages for respective product descriptions		
G	round terminal	_	_	_	_	_	_	_	•	
Operatin	g temperature range	-30°C t	o +85℃	-	-40℃ to +85°	C	-40℃ to 90℃	-30°C to	−30°C to +85°C	
А	utomotive use	_	_	_	•	_	0	_	_	
	Life Cycle	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$				* 2	* 2			
	Rating (max.) (Resistive load)				50mA	12V DC				
Electrical	Rating (min.) (Resistive load)		10µA 1V DC							
performance	Insulation resistance	100MΩ min. 100V DC 1min.								
	Voltage proof	100V AC 1min. 250V AC 1min. 100V AC 1min.								
Durability	Vibration	10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2 hours respectively								
Durability	Lifetime	Shall be in accordance with individual specifications.								
	Cold	-40℃ 96h								
Environmental performance	Dry heat	90°C 96h								
	Damp heat	60℃, 90 to 95%RH 96h								
	Page	208 209 210 211 212 213 215 21				216				

W: Width. The most outer dimension excluding terminal portion.

D : Depth. The most outer dimension excluding terminal portion. H : Height. The minimum dimension if there are variances.

ACT Switch $^{ extsf{TM}}$ Soldering Conditions $\cdots\cdots\cdots\cdots\cdots\cdots$ 25	9
ACT Switch™ Cautions \cdots 26	O

Notes

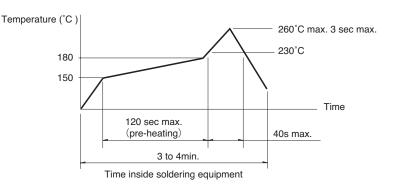
- 1. The automotive operating temperature range to be individually discussed upon request.
- 2. lacktriangle Indicates applicability to all products in the series, while \bigcirc indicates applicability to some products in the series.

TACT Switch™ Soldering Conditions

Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
 - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others.
 The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

	3.
Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

SKQJ, SKQK, SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

Manual Soldering

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

Notes

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)

